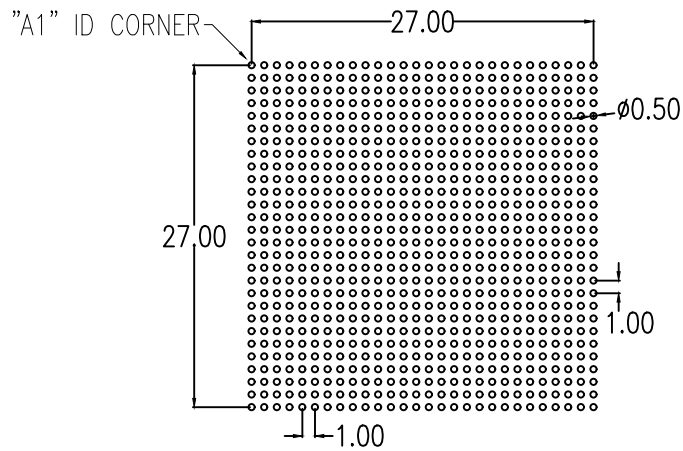


Δ $\phi 0.60 \pm 0.10$ (784x)

ϕ	$\phi 0.25(M)$	C	A	B
ϕ	$\phi 0.10(M)$	C		

NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1994
DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER,
- Δ PARALLEL TO PRIMARY DATUM -C-
- Δ SEATING PLANE AND PRIMARY DATUM -C- ARE DEFINED BY THE CONTACT POINTS OF THREE OR MORE SOLDER BALLS THAT SUPPORT THE DEVICE WHEN PLACED ON A TOP OF A PLANAR SURFACE.
- 4 ALL DIMENSIONS ARE IN MILLIMETERS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL DIMENSIONS ARE IN MM, ANGLES IN DEGREES.
- 2) TOP DOWN AS VIEW, AS VIEW ON PCB.
- 3) NSMD LAND PATTERN ASSUMED.
- 4) LAND PATTERN RECOMMENDATION AS PER IPC-7351B
GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

Package Revision History		
Date Created	Rev No.	Description
March 4, 2019	Rev 00	Initial Release